

ABSTRACT OF THE DISCLOSURE

A method for forming a recognition mark on the back surface of a substrate for a KGD that can be easily produced while manufacturing cost is low and permits repeated use of a substrate is provided. In the method, wiring patterns are formed on a surface of one side of an insulating substrate. The method includes step of forming a conductive pattern as a recognition mark on one surface where the wiring patterns are formed, and step of forming a through hole from a surface where the wiring pattern is not formed toward the conductive pattern. In the substrate, bumps connected with the KGD are formed on the surface on which the wiring patterns are not formed. Also, the conductive pattern may have a shape as the recognition mark or the through hole may have the shape as the recognition mark.